Specification of Thermoelectric Module

TEC1-12715

Description

The 127 couples, $50 \text{ mm} \times 50 \text{ mm}$ size single module which is made of our high performance ingot to achieve superior cooling performance and $70 \text{ }^{\circ}\text{C}$ or larger delta T max, is designed for superior cooling and heating applications. Beyond the standard below, we can design and manufacture the custom made module according to your special requirements.

Features

- No moving parts, no noise, and solid-state
- Compact structure, small in size, light in weight
- Environmental friendly
- RoHS compliant
- Precise temperature control
- Exceptionally reliable in quality, high performance

Application

- Food and beverage service refrigerator
- Portable cooler box for cars
- Liquid cooling
- Temperature stabilizer
- CPU cooler and scientific instrument
- Photonic and medical systems

Peformance Specification Sheet

Th (°C)	27	50	Hot side temperature at environment: dry air, N ₂	
$\mathrm{DT}_{\mathrm{max}}({}^{\circ}\!\!\mathrm{C})$	70	79	Temperature Difference between cold and hot side of the module when cooling capacity is zero at cold side	
U _{max} (Voltage)	16.0	17.2	Voltage applied to the module at DT _{max}	
$I_{max}(amps)$	15.0	15.0	DC current through the modules at DT _{max}	
Q _{C max} (Watts)	150.2	164.2	Cooling capacity at cold side of the module under $DT = 0$ °C	
AC resistance (ohms)	0.80	0.88	The module resistance is tested under AC	
Tolerance (%)	± 10		For thermal and electricity parameters	

Geometric Characteristics Dimensions in millimeters

Positive lead wire (Red) 16 AWG leads, PVC insulated Negative lead wire (Black) Cold side: Te See ordering option See ordering option See ordering option

Manufacturing Options

A. Solder:

- 1. T100: BiSn (Melting Point=138℃)
- 2. T200: CuSn (Melting Point= 227 °C)

B. Sealant:

- 1. NS: No sealing (Standard)
- 2. SS: Silicone sealant
- 3. EPS: Epoxy sealant
- 4. Customer specify sealing

C. Ceramics:

- 1. Alumin a $(Al_2O_3, white 96\%)(AlO)$
- 2. Aluminum Nitride (AlN)

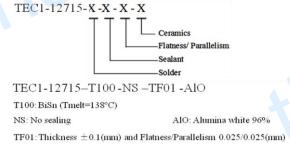
D. Ceramics Surface Options:

- 1. Blank ceramics (not metalized)
- 2. Metalized (Copper-Nickel plating)

Ordering Option

Suffix	Thickness (mm)	Flatness/ Parallelism (mm)	Lead wire length(mm) Standard/Optional length	
TF	0:4.0±0.1	0:0.035/0.035	125±1/Specify	
TF	1:4.0±0.05	1:0.025/0.025	125±1/Specify	
TF	2:4.0±0.03	2:0.015/0.015	125±1/Specify	
Eg. TF01: Thickness 4.0 ± 0.1 (mm) and Flatness $0.025 / 0.025$ (mm)				

Naming for the Module

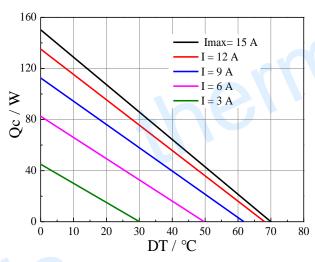


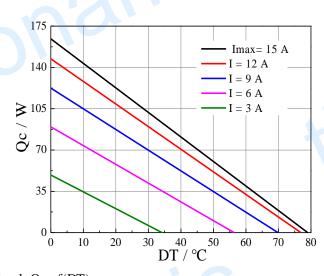
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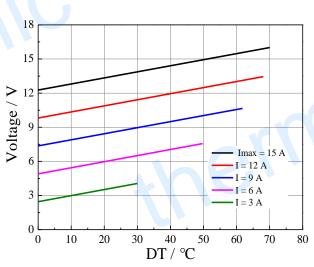


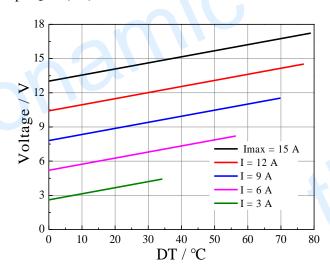
Performance Curves at Th=50 °C



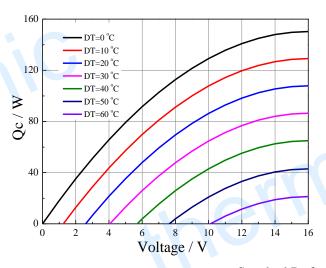


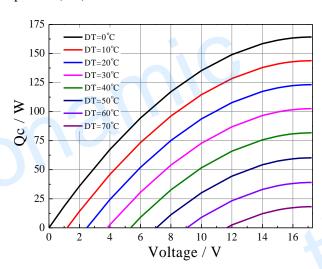
Standard Performance Graph Qc = f(DT)





Standard Performance Graph V = f(DT)



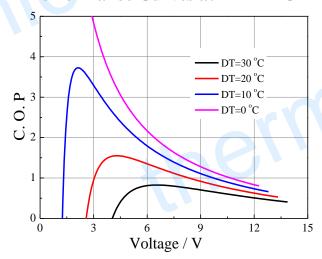


Standard Performance Graph Qc = f(V)

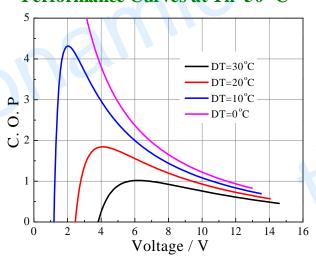
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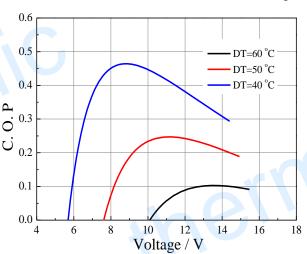
Performance Curves at Th=27 ℃

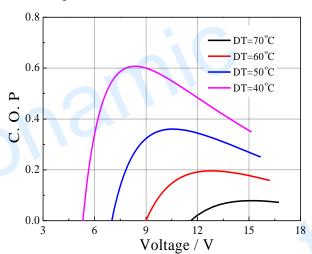


Performance Curves at Th=50 °C



Standard Performance Graph COP = f(V) of DT ranged from 0 to 30 °C





Standard Performance Graph COP = f(V) of DT ranged from 40 to 60/70 °C

Remark: The coefficient of performance (COP) is the cooling power Qc/Input power ($V \times I$).

Operation Cautions

- Cold side of the module sticked on the object being cooled
- Hot side of the module mounted on a heat radiator
- Operation or storage module below melting point of solder
- Operation below I_{max} or V_{max}
- Work under DC

Note: All specifications subject to change without notice.